ABSTRACT

MEGASONIC CLEANING SYSTEM

A system for cleaning semiconductor packages is provided which comprises a pickhead that is configured to hold the semiconductor packages in an array arrangement and a plurality of nozzles, each of which is constructed and arranged to project a separate jet of cleaning fluid upwardly against the semiconductor packages. A megasonic energy generator is coupled for imparting megasonic energy to the cleaning fluid and a driving device drives relative movement between the plurality of nozzles and the pickhead to direct the said jets to clean the array of packages on the pickhead.

(FIG. 2)